

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Xiao-Chun Mu et al.

Title: Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers

Docket No.: 884.798US1

Serial No.: 09/733,289

Filed: December 8, 2000

Due Date: N/A

Examiner: DiLinh Nguyen

Group Art Unit: 2814

MS Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

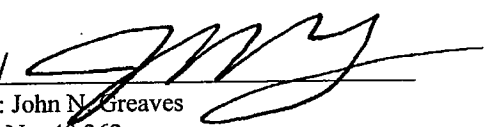
We are transmitting herewith the following attached items (as indicated with an "X"):

☒ Communication Concerning Related Applications (1 pg.).

☒ Supplemental Information Disclosure Statement (3 pgs.), Form 1449 (1 pg.), and copies of 3 cited documents.

SCHWEGMAN, LUNDBERG & WOESSNER, P.A.

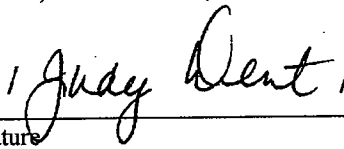
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 25th day of February, 2008.

JUDY DENT

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SCHWEGMAN, LUNDBERG & WOESSNER, P.A.

(GENERAL)